

WHAT IS CLAIMED IS:

1. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said resin composition comprising:

- 5 (a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature, Tg, of lower than 50 °C after polymerization; and
- 10 (b) a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with the oligomer compound (a) and that has a glass transition temperature, Tg, higher than at least 90 °C after polymerization; or
- 15 (b') a mixture of two or more low-molecular weight compounds that have in their molecule one reactive double bond capable of copolymerization with the oligomer compound (a) and that have a glass transition temperature, Tg, higher than 90 °C after polymerization.
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2. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said resin composition comprising:

SEARCHED - INDEXED

- (a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature, Tg, lower than 50°C after polymerization;
- 5 (b) a simple urethane adduct of hydroxyethyl acrylate or hydroxyethyl methacrylate and a diisocyanate; and
- (c) an optional low-molecular weight compound that has in its molecule at least one double bond capable of copolymerization with the oligomer compound (a).

RECORDED - 100%
THE STANDING COMMITTEE ON INTELLECTUAL PROPERTY